

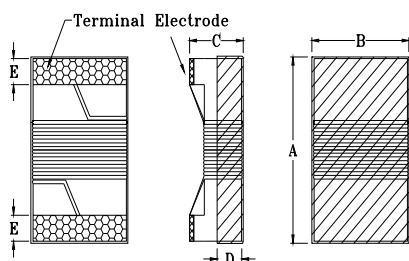
High Frequency Winding Type Chip Inductor SWI1008UV-SERIES

1. Features

1. Ceramic core wire wound construction.
2. No batch to batch variations in inductance
3. High Reliability due to ceramic wire wound construction.
4. High frequency application.
5. Small footprint as well as low profile.
6. 100% Lead(Pb) & Halogen-Free and RoHS compliant.
7. High reliability -Reliability tests comply with AEC-Q200
8. Operating temperature-55~+125℃ (Including self - temperature rise)



2. Dimensions



Size	A(mm)	B(mm)	C(mm)	D(mm)	E(mm)
SWI1008	2.92 max.	2.79 max.	2.20 max.	1.20 ref.	0.55±0.10

Unit:mm

3. Part Numbering

SWI	1008	U	V	-	10N	J
A	B	C	D		E	F

A: Series

B: Dimension

LxW

C: Material

D: Category Code

V=Vehicle

E: Inductance

10N=10nH

F: Inductance Tolerance

G=±2%, J=±5%, K=±10%

4. Specification

Part Number	Inductance (nH)	Tolerance	Test Frequency (Hz)	Q @ Test Freq. min.	Rated Current (mA) max.	DCR (Ω) max.	SRF (MHz) min.
SWI1008UV-10N□	10	G, J, K	0.1V/50M	50/500	1000	0.08	4100
SWI1008UV-12N□	12	G, J, K	0.1V/50M	50/500	1000	0.09	3300
SWI1008UV-15N□	15	G, J, K	0.1V/50M	50/500	1000	0.18	2500
SWI1008UV-18N□	18	G, J, K	0.1V/50M	50/350	1000	0.11	2500
SWI1008UV-22N□	22	G, J, K	0.1V/50M	55/350	1000	0.12	2400
SWI1008UV-27N□	27	G, J, K	0.1V/50M	55/350	1000	0.13	1600
SWI1008UV-33N□	33	G, J, K	0.1V/50M	60/350	1000	0.14	1600
SWI1008UV-39N□	39	G, J, K	0.1V/50M	60/350	1000	0.15	1500
SWI1008UV-47N□	47	G, J, K	0.1V/50M	65/350	1000	0.16	1500
SWI1008UV-56N□	56	G, J,K	0.1V/50M	65/350	1000	0.18	1300
SWI1008UV-68N□	68	G, J,K	0.1V/50M	65/350	1000	0.20	1300
SWI1008UV-82N□	82	G, J,K	0.1V/50M	60/350	1000	0.22	1000

Part Number	Inductance (nH)	Tolerance	Test Frequency (Hz)	Q @ Test Freq. min.	Rated Current (mA) max.	DCR (Ω) max.	SRF (MHz) min.
SWI1008UV-R10□	100	G, J,K	0.1V/25M	60/350	650	0.56	1000
SWI1008UV-R12□	120	G, J,K	0.1V/25M	60/350	650	0.63	950
SWI1008UV-R15□	150	G, J,K	0.1V/25M	45/100	580	0.70	850
SWI1008UV-R18□	180	G, J,K	0.1V/25M	45/100	620	0.77	750
SWI1008UV-R22□	220	G, J,K	0.1V/25M	45/100	500	0.84	700
SWI1008UV-R27□	270	G, J,K	0.1V/25M	45/100	500	0.91	600
SWI1008UV-R33□	330	G, J,K	0.1V/25M	45/100	450	1.05	570
SWI1008UV-R39□	390	G, J,K	0.1V/25M	45/100	470	1.12	500
SWI1008UV-R47□	470	G, J,K	0.1V/25M	45/100	470	1.19	450
SWI1008UV-R56□	560	G, J,K	0.1V/25M	45/100	400	1.33	415
SWI1008UV-R62□	620	G, J,K	0.1V/25M	45/100	300	1.40	375
SWI1008UV-R68□	680	G, J,K	0.1V/25M	45/100	400	1.47	375
SWI1008UV-R75□	750	G, J,K	0.1V/25M	45/100	360	1.54	360
SWI1008UV-R82□	820	G, J,K	0.1V/25M	45/100	400	1.61	350
SWI1008UV-R91□	910	G, J,K	0.1V/25M	35/50	380	1.68	320
SWI1008UV-1R0□	1000	G, J,K	0.1V/25M	35/50	370	1.75	290
SWI1008UV-1R2□	1200	G, J,K	0.1V/7.9M	35/50	310	2.00	250
SWI1008UV-1R5□	1500	G, J,K	0.1V/7.9M	28/50	330	2.23	200
SWI1008UV-1R8□	1800	G, J,K	0.1V/7.9M	28/50	300	2.60	160
SWI1008UV-2R2□	2200	G, J,K	0.1V/7.9M	28/50	280	2.80	160
SWI1008UV-2R7□	2700	G, J,K	0.1V/7.9M	22/25	290	3.20	140
SWI1008UV-3R3□	3300	G, J,K	0.1V/7.9M	22/25	290	3.40	110
SWI1008UV-3R9□	3900	G, J,K	0.1V/7.9M	20/25	260	3.60	100
SWI1008UV-4R7□	4700	G, J,K	0.1V/7.9M	18/7.9	200	4.00	32
SWI1008UV-5R6□	5600	G, J,K	0.1V/7.9M	18/7.9	200	4.00	25
SWI1008UV-6R8□	6800	G, J,K	0.1V/7.9M	18/7.9	200	4.90	21
SWI1008UV-8R2□	8200	G, J,K	0.1V/7.9M	16 /7.9	170	6.00	16
SWI1008UV-100□	10000	G, J,K	0.1V/2.52M	15/7.9	170	8.00	14

5. Recommended PC Board Pattern

Chip size						Land Patterns For Reflow Soldering			
Series	Type	A(mm)	B(mm)	C(mm)	D(mm)	E(mm)	L(mm)	G(mm)	H(mm)
SWI	1008	2.92max	2.79max	2.20max	1.20 ref	0.55±0.1	3.31	1.526	2.54

